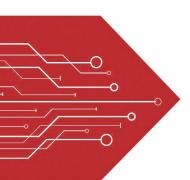
# MSKSEMI















**ESD** 

TVS

TSS

MOV

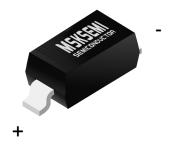
**GDT** 

**PLED** 

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SOD-123

#### **FEATURES**

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- **High Conductance**

### Maximum Ratings and Electrical Characteristics, Single Diode @T<sub>A</sub>=25℃

Parameter	Symbol	Limits	Unit
Non-Repetitive Peak reverse voltage	$V_{RM}$	100	V
Peak Repetitive Peak reverse voltage	$V_{RRM}$		
Working Peak Reverse Voltage	$V_{RWM}$	75	V
DC Blocking Voltage	$V_{R}$		
RMS Reverse Voltage	$V_{R(RMS)}$	53	V
Forward Continuous Current	I <sub>FM</sub>	300	mA
Average Rectified Output Current	Ιο	150	mA
Peak forward surge current @=1.0µs	I <sub>FSM</sub>	2.0	٨
@=1.0s		1.0	А
Power Dissipation	Pd	400	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	315	°C/W
Junction temperature	Tj	125	℃
Storage temperature	T <sub>STG</sub>	-65~+150	℃

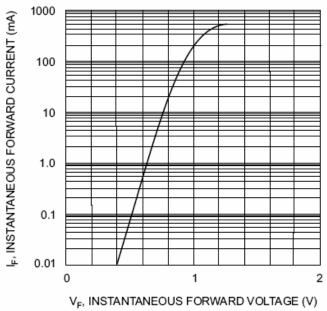
### Electrical Ratings @T<sub>A</sub>=25℃

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V <sub>F1</sub>			0.715	V	I <sub>F</sub> =1mA
	V <sub>F2</sub>			0.855	V	I <sub>F</sub> =10mA
	V <sub>F3</sub>			1.0	V	I <sub>F</sub> =50mA
	V <sub>F4</sub>			1.25	V	I <sub>F</sub> =150mA
Reverse current	I <sub>R1</sub>			1	μA	V <sub>R</sub> =75V
	I <sub>R2</sub>			25	nA	V <sub>R</sub> =20V
Capacitance between terminals	Ст			2	pF	V <sub>R</sub> =0V,f=1MHz
Reverse Recovery Time	t <sub>rr</sub>			4	ns	I <sub>F</sub> =I <sub>R</sub> =10mA
Travelse receivery filling						Irr=0.1 $XI_R$ , $R_L$ =100 $\Omega$



# **Typical Characteristics**

#### 1N4148W-7-MS/BAV16W-7-MF



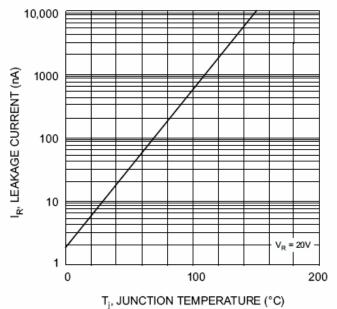
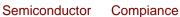


Fig. 1 Forward Characteristics

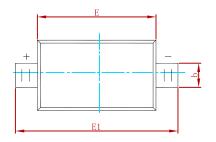
Fig. 2 Leakage Current vs Junction Temperature

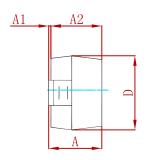


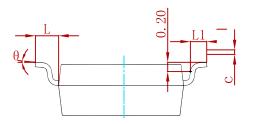




### **PACKAGE MECHANICAL DATA**

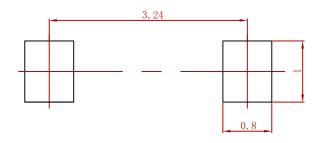






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.450	0.650	0.018	0.026	
С	0.080	0.150	0.003	0.006	
D	1.500	1.700	0.059	0.067	
Е	2.600	2.800	0.102	0.110	
E1	3.550	3.850	0.140	0.152	
L	0.500 REF		0.020 REF		
L1	0.250	0.450	0.010	0.018	
θ	0°	8°	0°	8°	

### **Suggested Pad Layout**



- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

### **REEL SPECIFICATION**

P/N	PKG	QTY	MARK
1N4148W-7-MS	SOD-123	3000	T4
BAV16W-7-MS	SOD-123	3000	T6





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